

PROCESS AND APPARATUS FOR TREATING GAS CONTAINING
FLUORINE-CONTAINING COMPOUNDS AND CO.

ABSTRACT OF THE DISCLOSURE

The purpose of the present invention is to provide a
5 process and an apparatus for efficiently treating a gas
containing fluorine-containing compounds and CO to be
discharged, for example, from the step of dry cleaning the
inner surfaces and the like of a semiconductor
manufacturing apparatus or the step of etching various
10 types of formed films such as oxide films in the
semiconductor industry. In order to accomplish the above-
mentioned purpose, the gas treating process according to
the present invention is a process for treating a gas
containing fluorine-containing compounds and CO which
15 comprises contacting the above described gas with O₂ and
H₂O at a temperature of 850°C or higher to oxidize the CO
to CO₂; and then contacting the gas with γ-alumina at a
temperature of 600 to 900°C to decompose the fluorine-
containing compounds.